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(21)Application number : 11-137018 (71)Applicant : NGK SPARK PLUG CO LTD  
(22)Date of filing : 18.05.1999 (72)Inventor : OGAWA KOJU

**(54) WIRING BOARD AND MANUFACTURE THEREOF WITH MOUNTED ELECTRONIC COMPONENT**

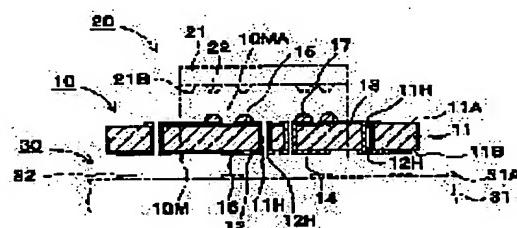
**(57)Abstract:**

**PROBLEM TO BE SOLVED:** To provide a wiring board easy to manufacture where voids are hardly generated in resin when resin is injected in a part between the wiring board and electronic components after the electronic components are mounted, and the manufacturing method of a wiring board mounting electronic components where voids are hardly generated in resin.

**SOLUTION:** This board is a wiring board capable of mounting an IC chip 20 on a mounting surface 10MA in a mounting part 10M. Solder bumps 17 and surface pads 15, which can be connected with bumps 22 of the IC chip 20, are arranged on the mounting surface 10MA.

Hollow cylindrical through-hole conductor 12, which has a linkage hole 12H interlinking the mounting surface 10MA with its rear 11B in the inside periphery and is electrically connected with the solder bump 17 and the surface pad 15, is formed in the mounting part 10M.

After the IC chip 20 is mounted on the mounting surface 10MA, resin injected while air is made to escape from the linkage hole 12H, and a filled resin layer having no void.



## **LEGAL STATUS**

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